## Features

- 0603 0.20mm SMD LED
- High Brightness
- AlInGaP / InGaN Technology
- Small package
- High reliability
- Clear Lens

## Applications

- Consumer Electronics
- Wearables
- Automobile After Market
- Industrial Equipment

## Description

The IN-S63ET series is a popular low profile 0603 package with versatile design capabilities. It is a PCB type molding style LED which can be used in various applications.

## Recommended Solder Pattern

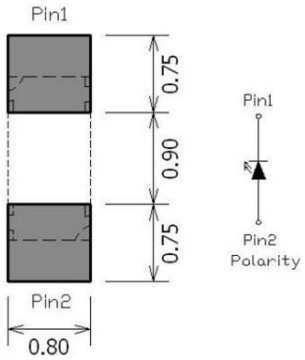
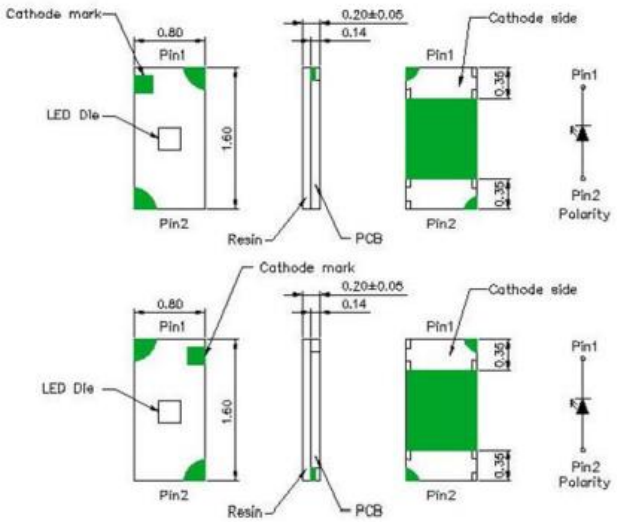



**Figure 1. IN-S63ET Solder Pattern**

## Package Dimensions in mm




Notes.
1. All dimensions are in millimeters.
2. Tolerance is ± 0.10 mm unless otherwise noted

**Figure 2. IN-S63ET Package Dimensions**

## Absolute Maximum Rating at 25°C (Note 1)

| Product | Emission Color | $P_d$ (mW) | $I_F$ (mA) | $I_{FP}$* (mA) | $V_R$ (V) | $T_{OP}$ (°C) | $T_{ST}$ (°C) |
|---|---|---|---|---|---|---|---|
| IN-S63ETR | Red | 42 | 20 | 100 | 5 | -40°C~+85°C | -40°C~+100°C |
| IN-S63ETYG | Yellow Green | 48 | 20 | 100 | 5 | -40°C~+85°C | -40°C~+100°C |
| IN-S63ETY | Yellow | 48 | 20 | 100 | 5 | -40°C~+85°C | -40°C~+100°C |
| IN-S63ETA | Amber | 48 | 20 | 100 | 5 | -40°C~+85°C | -40°C~+100°C |
| IN-S63ETB | Blue | 78 | 20 | 80 | 5 | -40°C~+85°C | -40°C~+100°C |
| IN-S63ETG | Green | 78 | 20 | 80 | 5 | -40°C~+85°C | -40°C~+100°C |
| IN-S63ETUW | White | 66 | 20 | 80 | 5 | -40°C~+85°C | -40°C~+100°C |

### Notes
1. Condition for IFP is pulse of 1/10 duty and 0.1msec width

## ESD Precaution

ATTENTION: Electrostatic Discharge (ESD) protection

The symbol above denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are STATIC SENSITIVE devices. ESD precaution must be taken during design and assembly.
If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

Please be advised that normal static precautions should be taken in the handling and assembly of this device to prevent damage or degradation which may be induced by electrostatic discharge (ESD).

## Electrical Characteristics $T_A$ = 25℃ (Note 1)

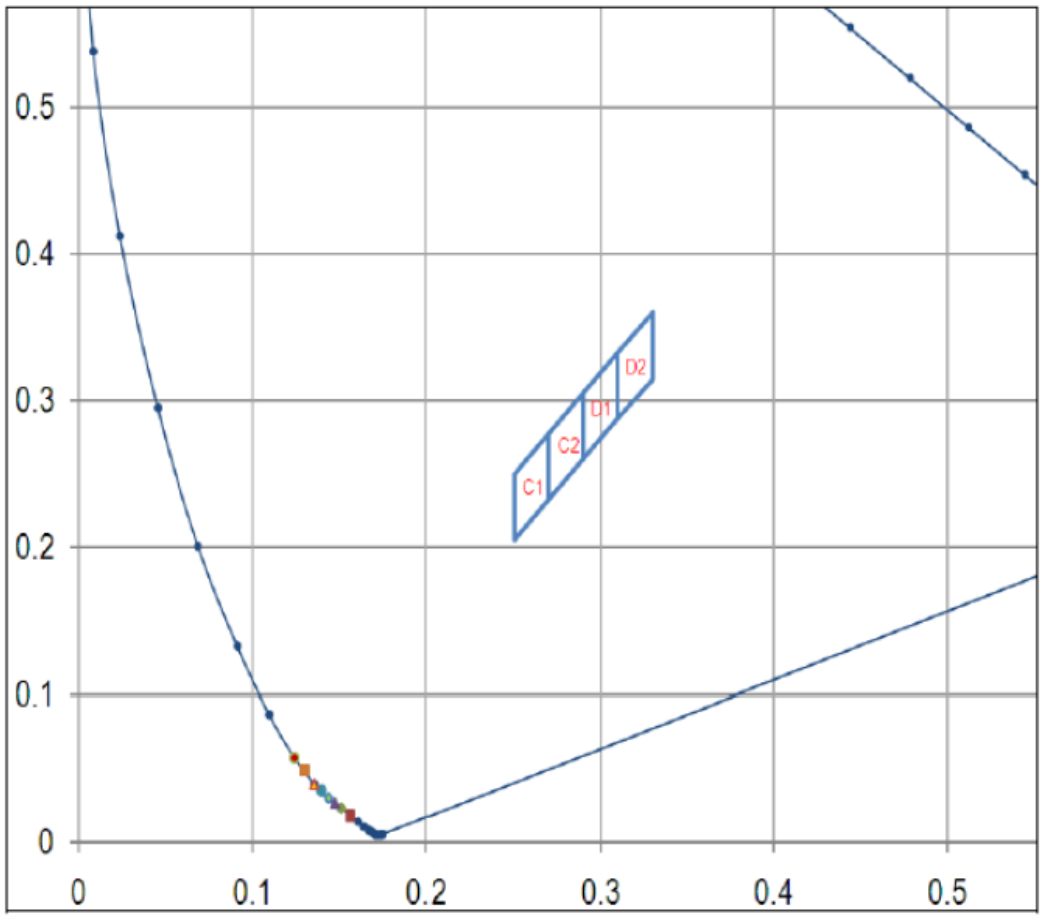
| Product | Emission Color | $I_F$(mA) | $V_F$(V) | | λ (nm) | | | Viewing Angle | $I^*_V$(mcd) |
|---|---|---|---|---|---|---|---|---|---|
| | | | typ. | max | $\lambda_D$ | $\lambda_P$ | △λ | $2\theta_{1/2}$ | typ. |
| IN-S63ETR | Red | 20 | 2.0 | 2.4 | 624 | 632 | 20 | X=105 Y=120 | 71.5 |
| IN-S63ETYG | Yellow Green | 20 | 2.1 | 2.4 | 571 | 573 | 15 | X=105 Y=120 | 71.5 |
| IN-S63ETY | Yellow | 20 | 2.0 | 2.4 | 589 | 591 | 20 | X=105 Y=120 | 71.5 |
| IN-S63ETA | Amber | 20 | 2.0 | 2.4 | 605 | 611 | 17 | X=105 Y=120 | 71.5 |
| IN-S63ETB | Blue | 20 | 3.3 | 3.9 | 470 | 468 | 40 | X=105 Y=120 | 112.5 |
| IN-S63ETG | Green | 20 | 3.3 | 3.9 | 525 | 520 | 30 | X=105 Y=120 | 360 |
| IN-S63ETUW | White | 20 | 3.1 | 3.5 | X=0.290 Y=0.285 | - | - | X=120 Y=135 | 1250 |

### Notes

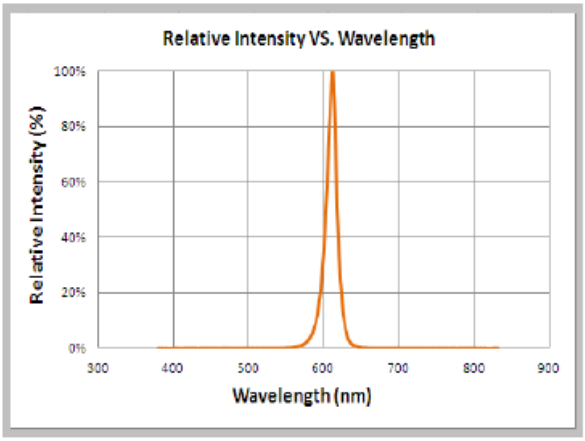
1. Performance guaranteed only under conditions listed in above tables.

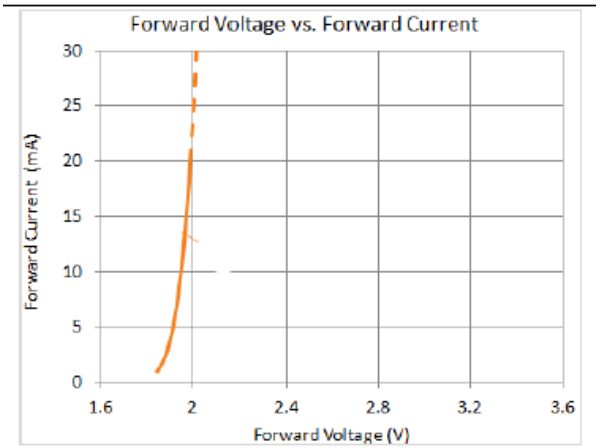
## Chromaticity Bin (for White only)

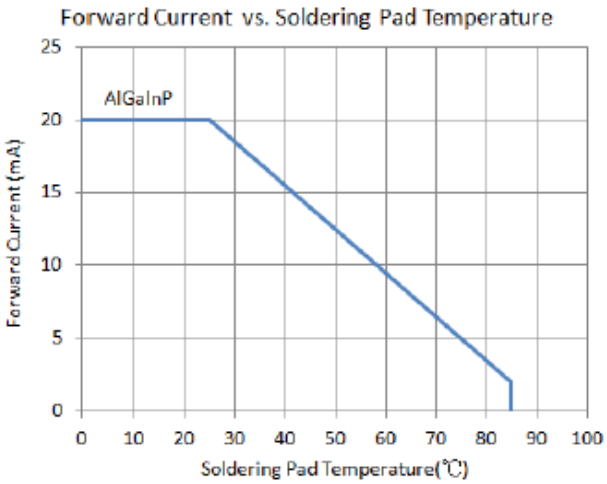
| Bin Code | CIE-X | CIE-Y | Bin Code | CIE-X | CIE-Y |
|---|---|---|---|---|---|
| C1 | 0.2500 | 0.2050 | C2 | 0.2700 | 0.2325 |
| | 0.2500 | 0.2500 | | 0.2700 | 0.2775 |
| | 0.2700 | 0.2775 | | 0.2900 | 0.3050 |
| | 0.2700 | 0.2325 | | 0.2900 | 0.2600 |
| Bin Code | CIE-X | CIE-Y | Bin Code | CIE-X | CIE-Y |
| D1 | 0.2900 | 0.2600 | D2 | 0.3100 | 0.2875 |
| | 0.2900 | 0.3025 | | 0.3100 | 0.3325 |
| | 0.3100 | 0.3325 | | 0.3300 | 0.3600 |
| | 0.3100 | 0.2875 | | 0.3300 | 0.3150 |

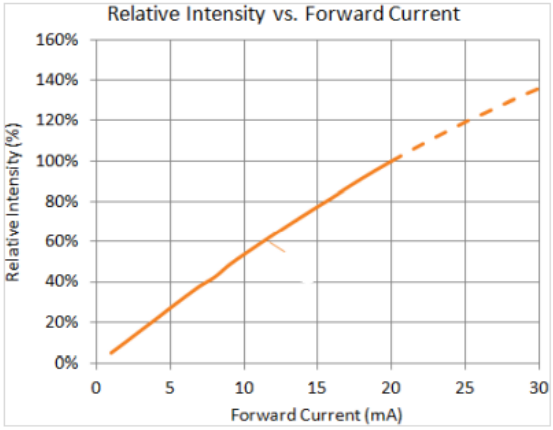


## Typical Characteristic Curves –A

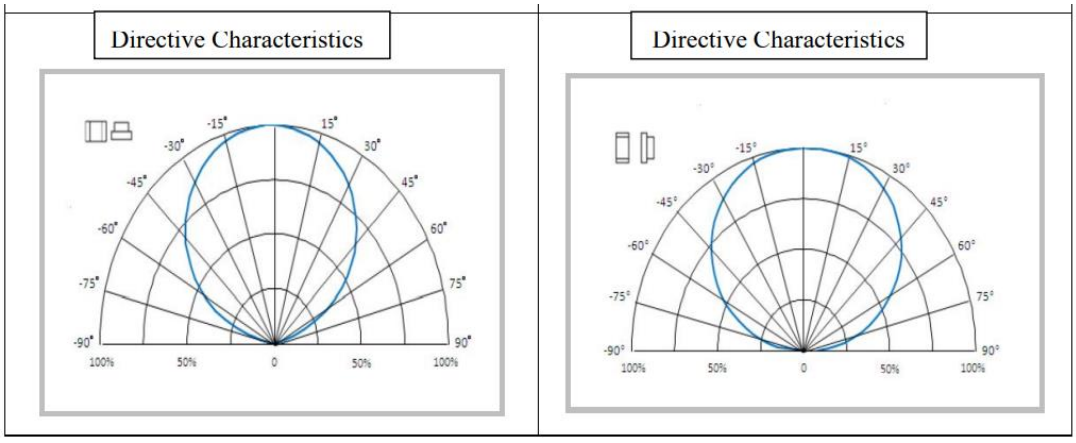


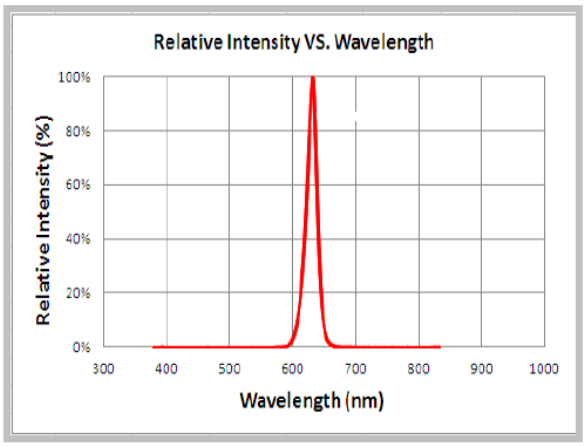



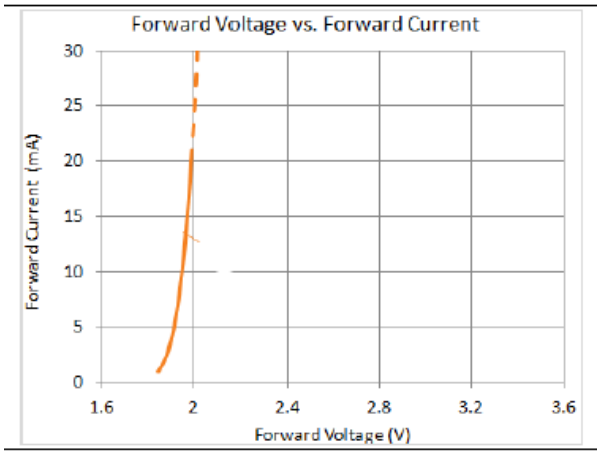



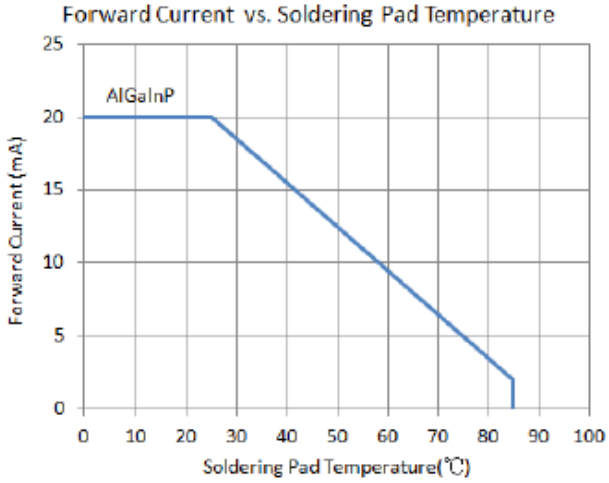

## Typical Characteristic Curves – Radiation Pattern

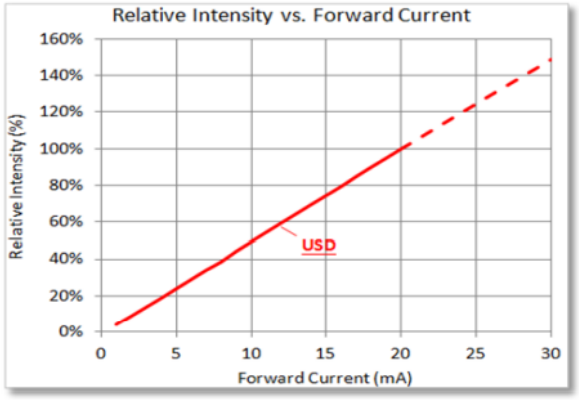


## Typical Characteristic Curves –R

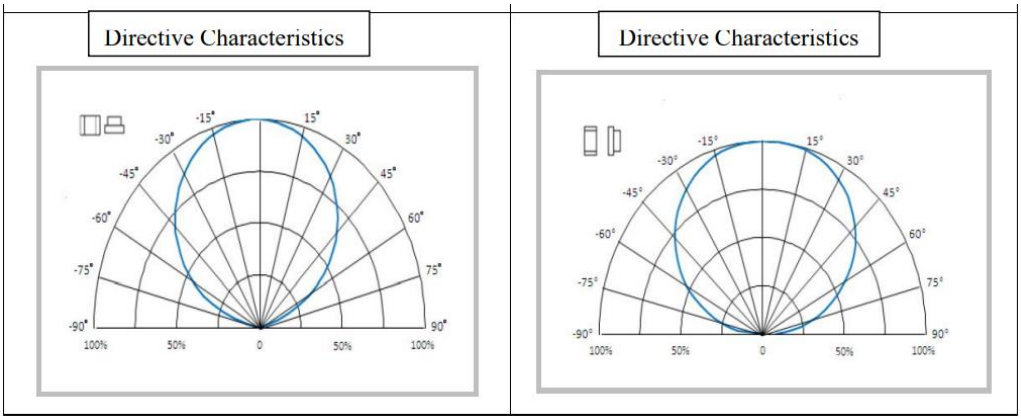


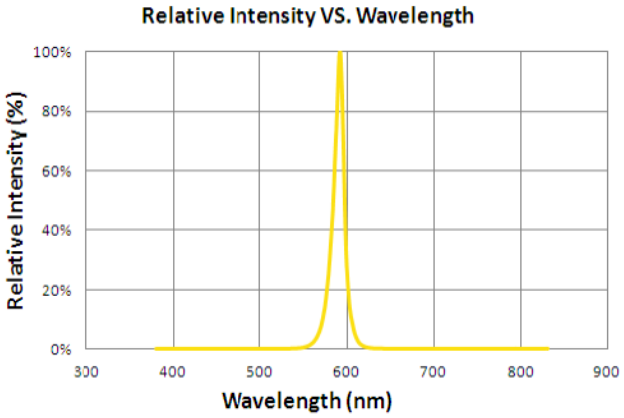



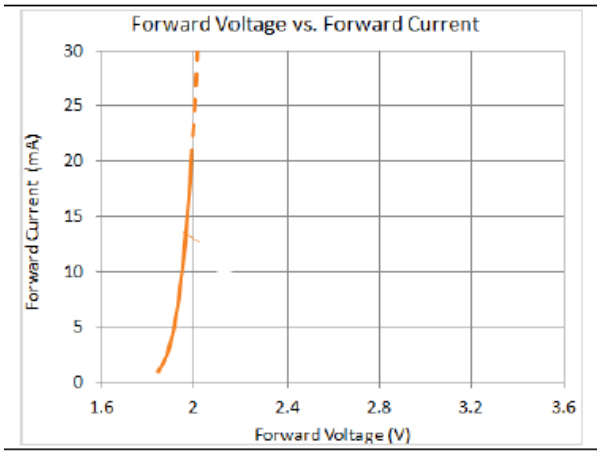



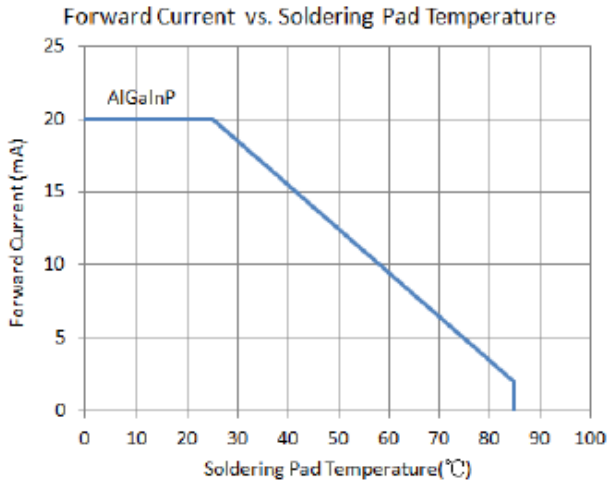

## Typical Characteristic Curves – Radiation Pattern

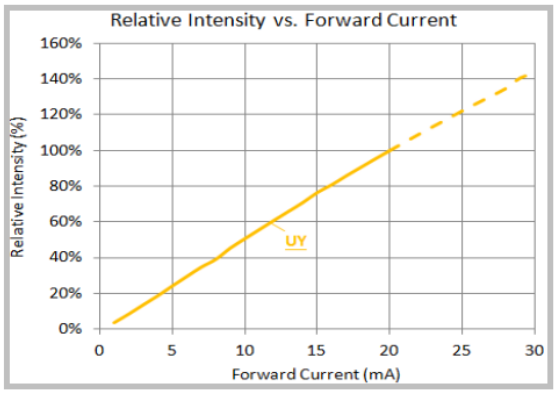


## Typical Characteristic Curves –Y

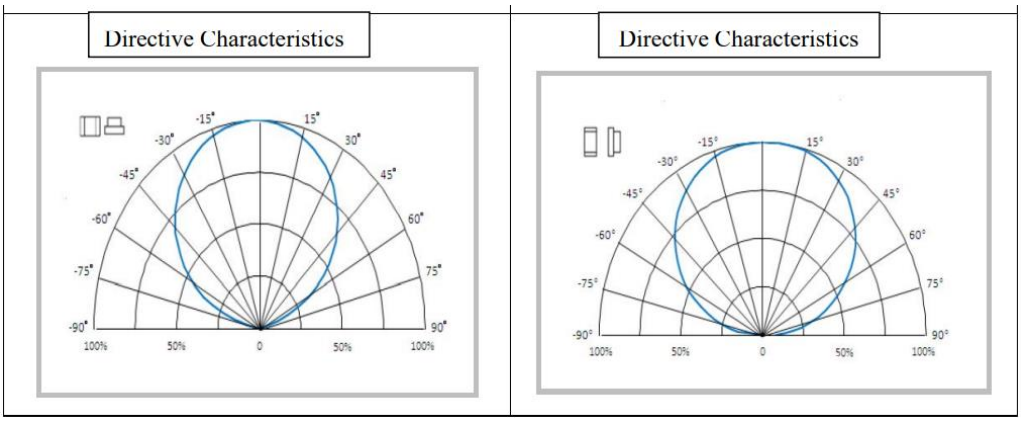


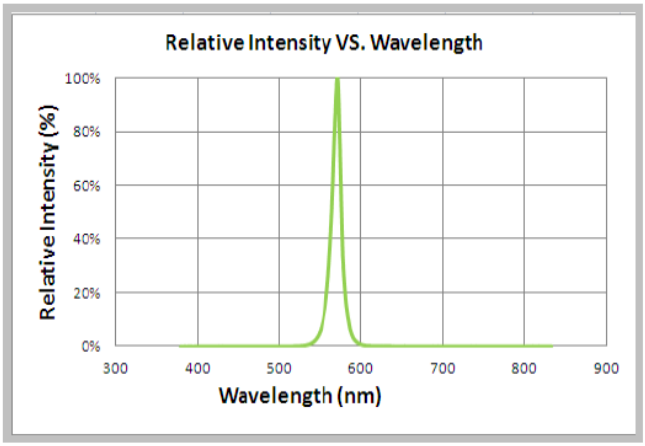



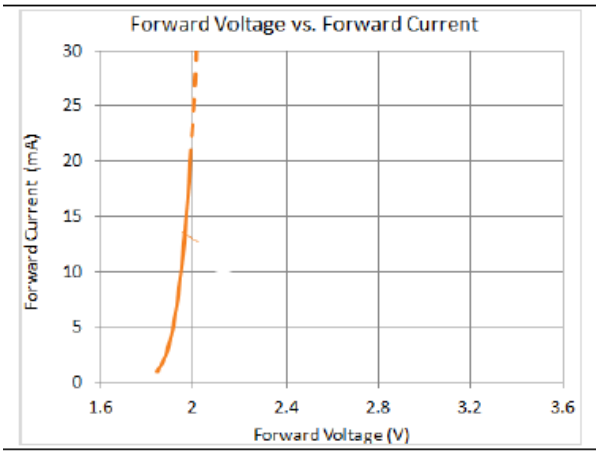



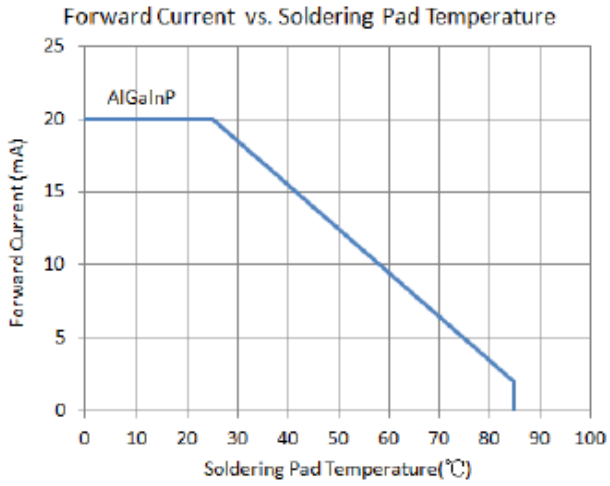

## Typical Characteristic Curves – Radiation Pattern

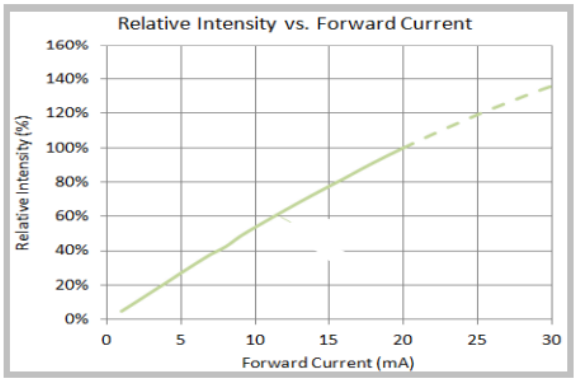


## Typical Characteristic Curves –YG

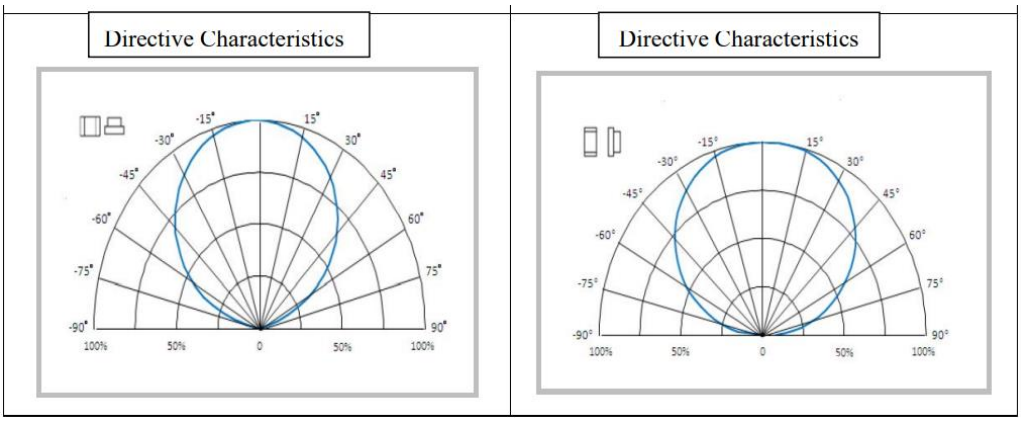


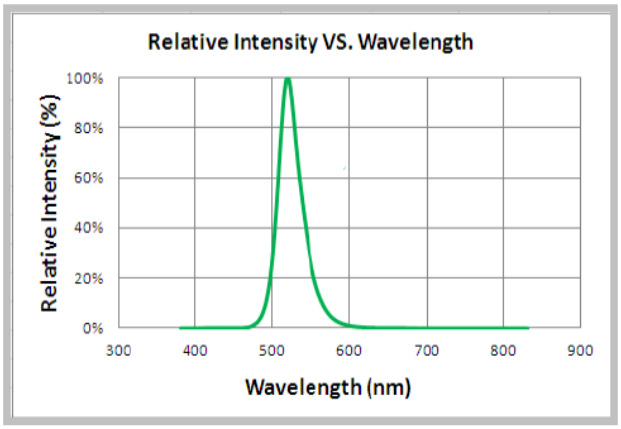



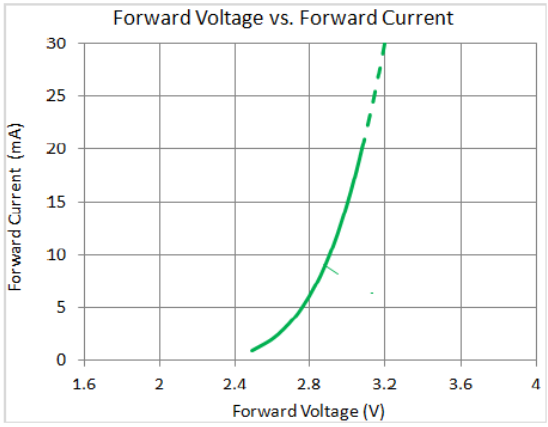



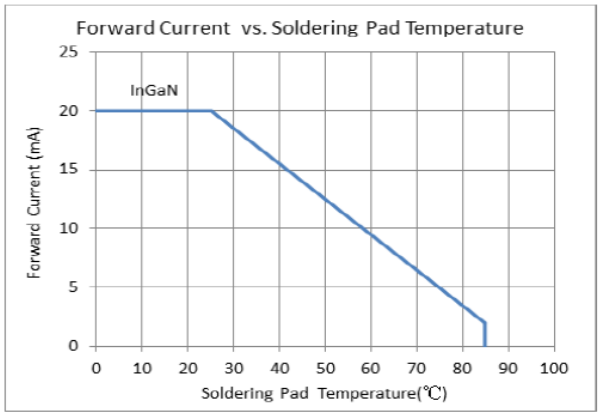

## Typical Characteristic Curves – Radiation Pattern

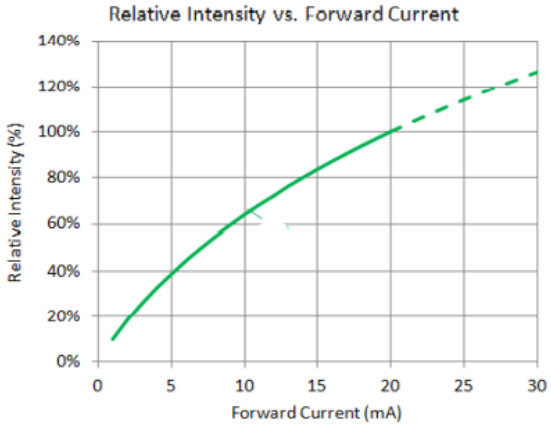


## Typical Characteristic Curves –G

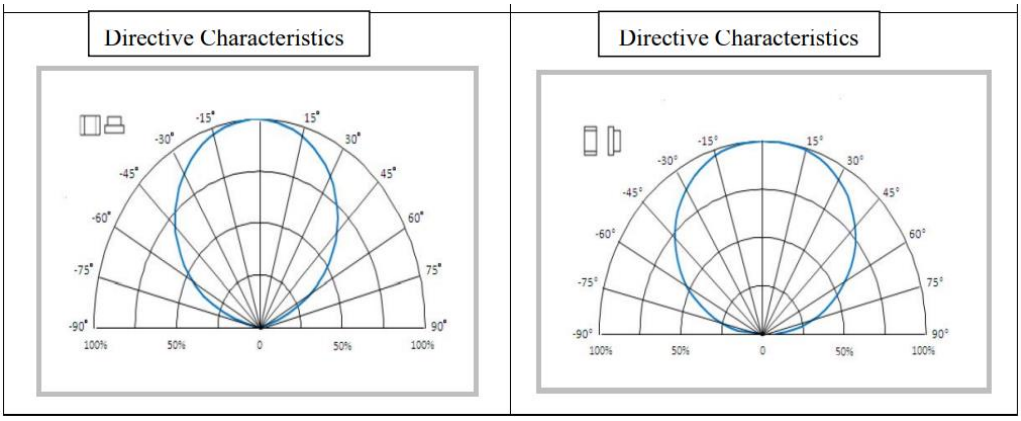


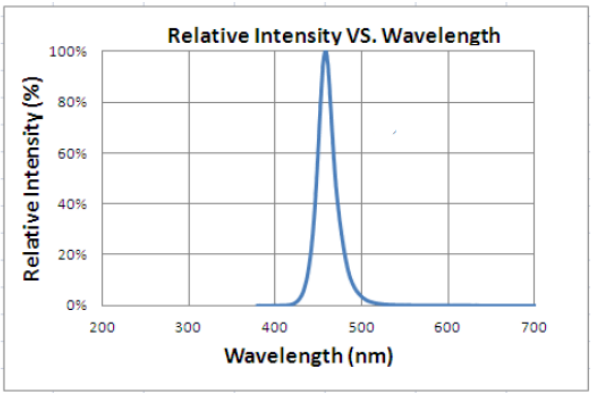



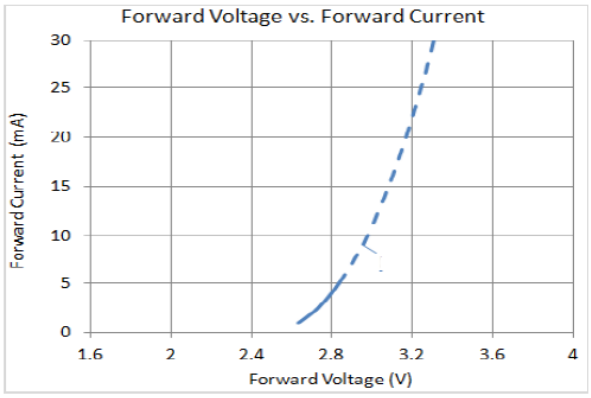



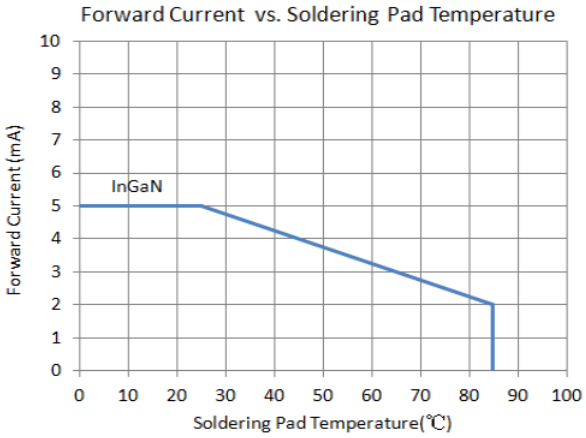

## Typical Characteristic Curves – Radiation Pattern

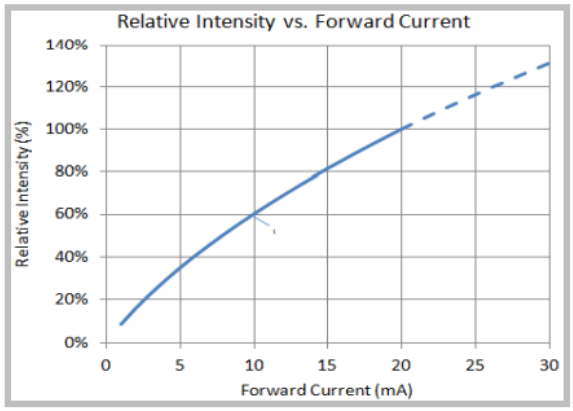


## Typical Characteristic Curves –B

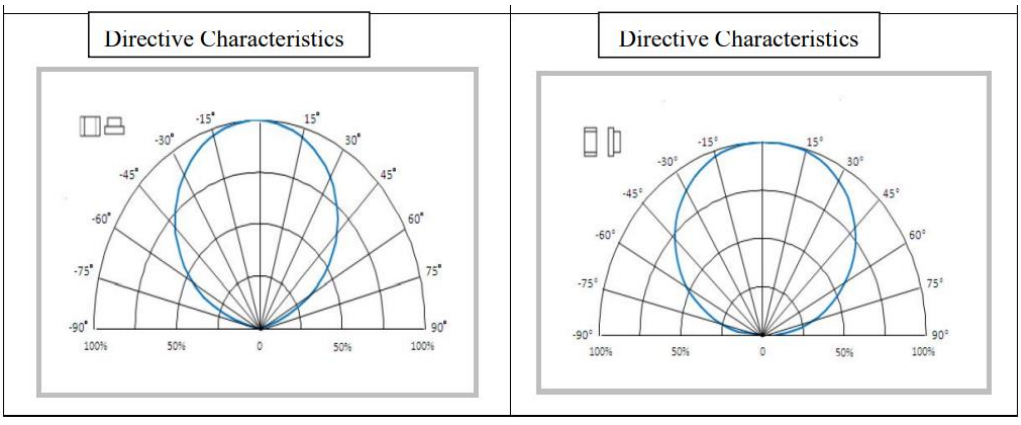


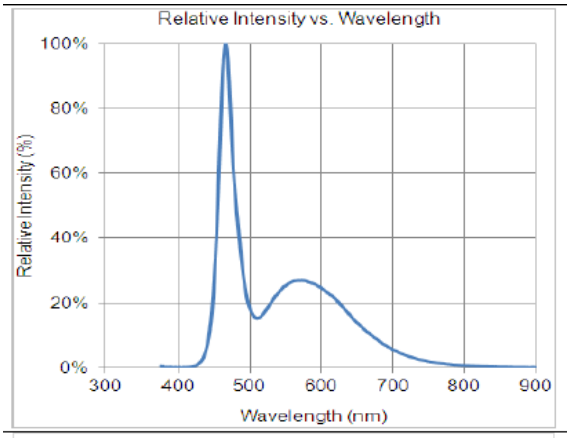



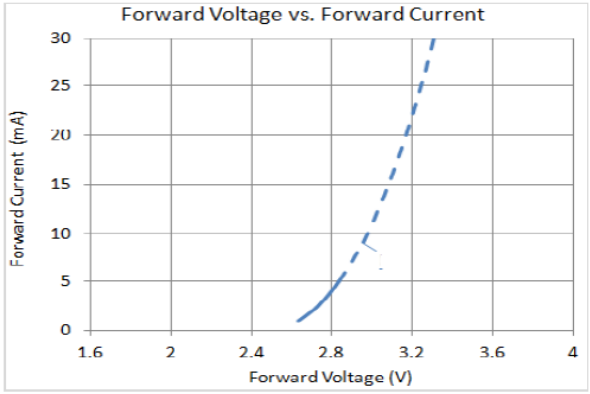



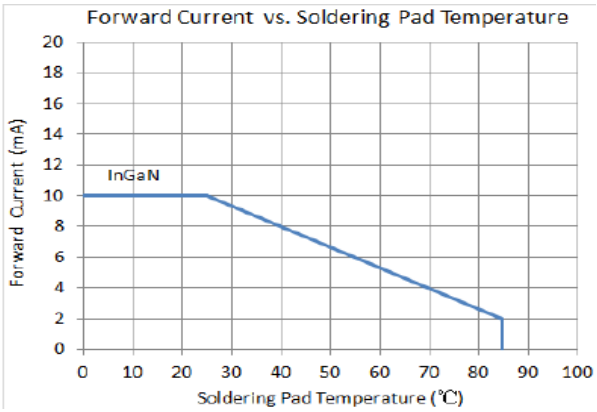

## Typical Characteristic Curves – Radiation Pattern

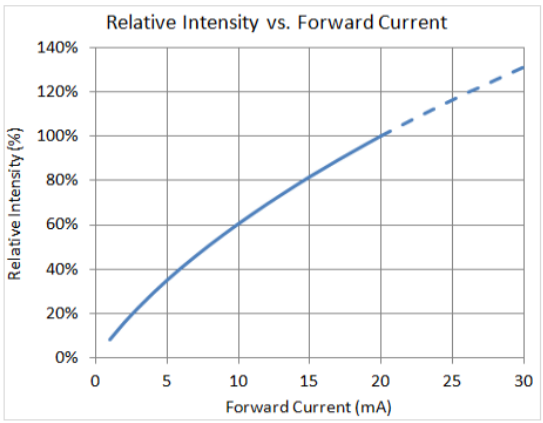


## Typical Characteristic Curves –W

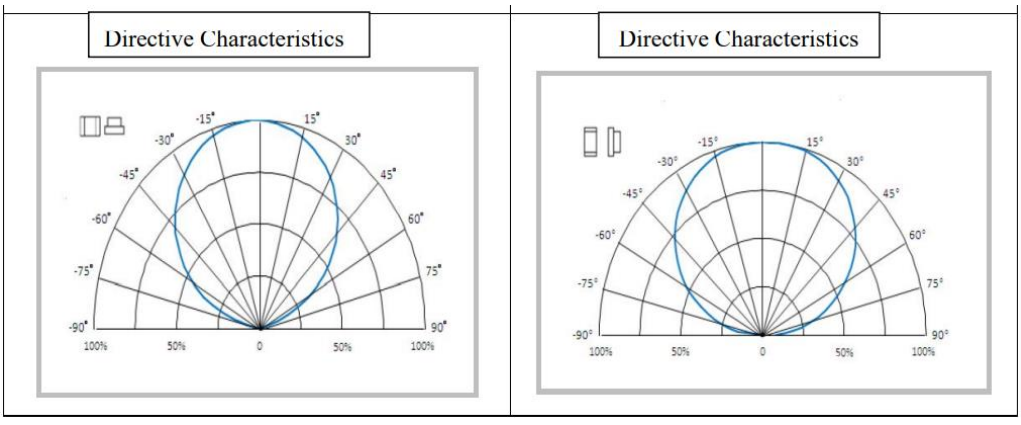


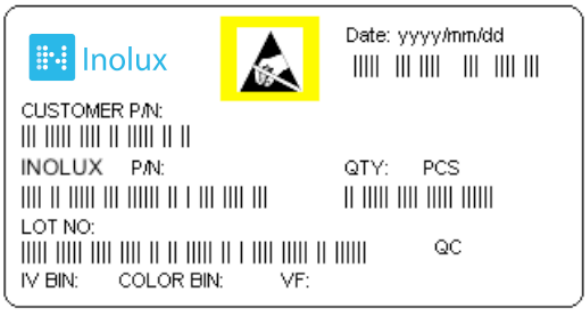

## Typical Characteristic Curves – Radiation Pattern



## Ordering Information

| Product | Emission Color | Technology | Test Current $I_F$ (mA) | Luminous Intensity $I_V$ (mcd) (Typ.) | Forward Voltage $V_F$ (V) (Typ.) | Orderable Part Number |
|---|---|---|---|---|---|---|
| IN-S63ETR | Red | AlInGaP | 20 | 71.5 | 2.0 | IN-S63ETR |
| IN-S63ETYG | Yellow Green | AlInGaP | 20 | 71.5 | 2.1 | IN-S63ETYG |
| IN-S63ETY | Yellow | AlInGaP | 20 | 71.5 | 2.0 | IN-S63ETY |
| IN-S63ETA | Amber | AlInGaP | 20 | 71.5 | 2.0 | IN-S63ETA |
| IN-S63ETB | Blue | InGaN | 20 | 112.5 | 3.3 | IN-S63ETB |
| IN-S63ETG | Green | InGaN | 20 | 360 | 3.3 | IN-S63ETG |
| IN-S63ETUW | White | InGaN | 20 | 1250 | 3.1 | IN-S63ETUW |

## Label Specifications




## Inolux P/N:

| I | N | - | S | 6 | 3 | E | T | | - | | - | - | - | - | - |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | | | Material | Package | | Variation | Orientation | Current | Lens | Color | | Customized Stamp-off | | | |
| Inolux SMD | | | S = PCB Type | 63E = 1.6 x 0.8 x 0.20mm | | | T = Top Mount | (Blank) =20mA | (Blank) = Clear U = Diffused | R=624nm A=605nm Y=590nm YG=570nm G=520nm B=470nm W=White | | - | | | |

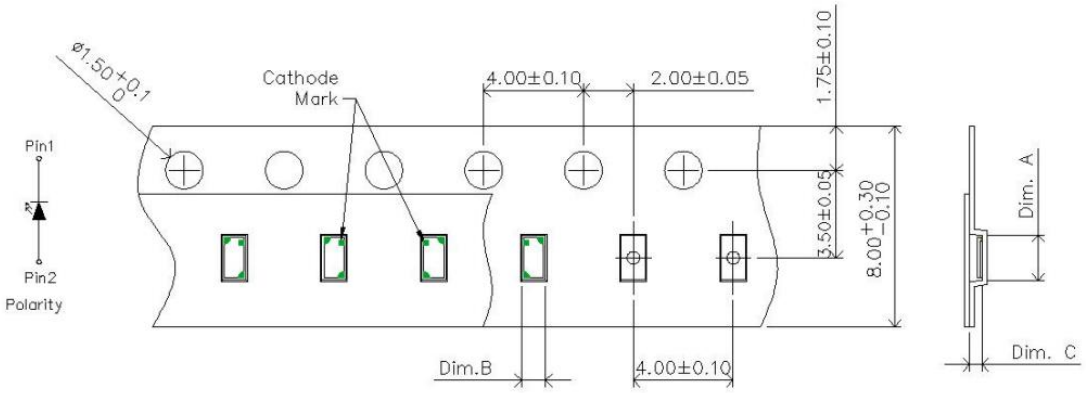
### Lot No.:

| Z | 2 | 0 | 1 | 7 | 01 | 24 | 001 |
|---|---|---|---|---|---|---|---|
| Internal Tracker | Year (2017, 2018, .....) | | | | Month | Date | Serial |

## Packaging Information: 3000pcs Per Reel

**Packaging**

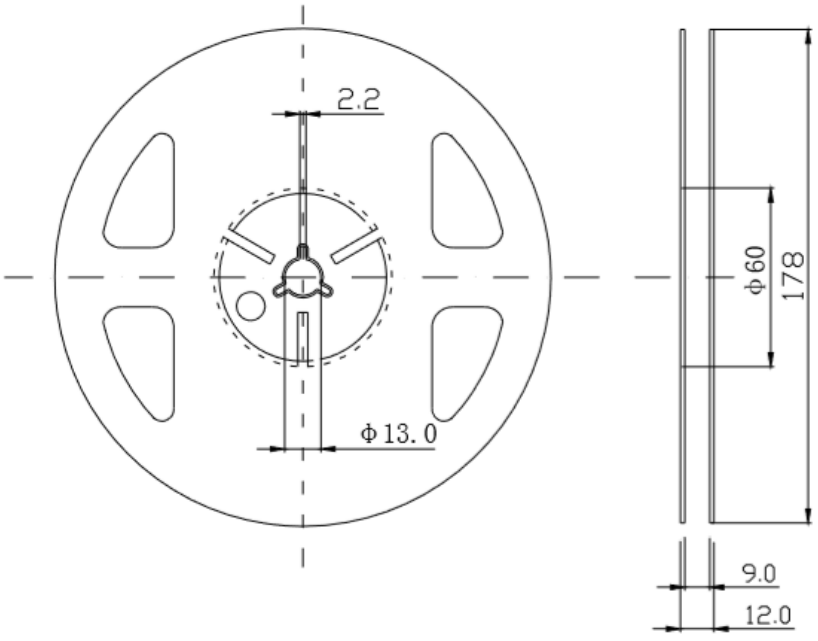
**Tape Dimension**



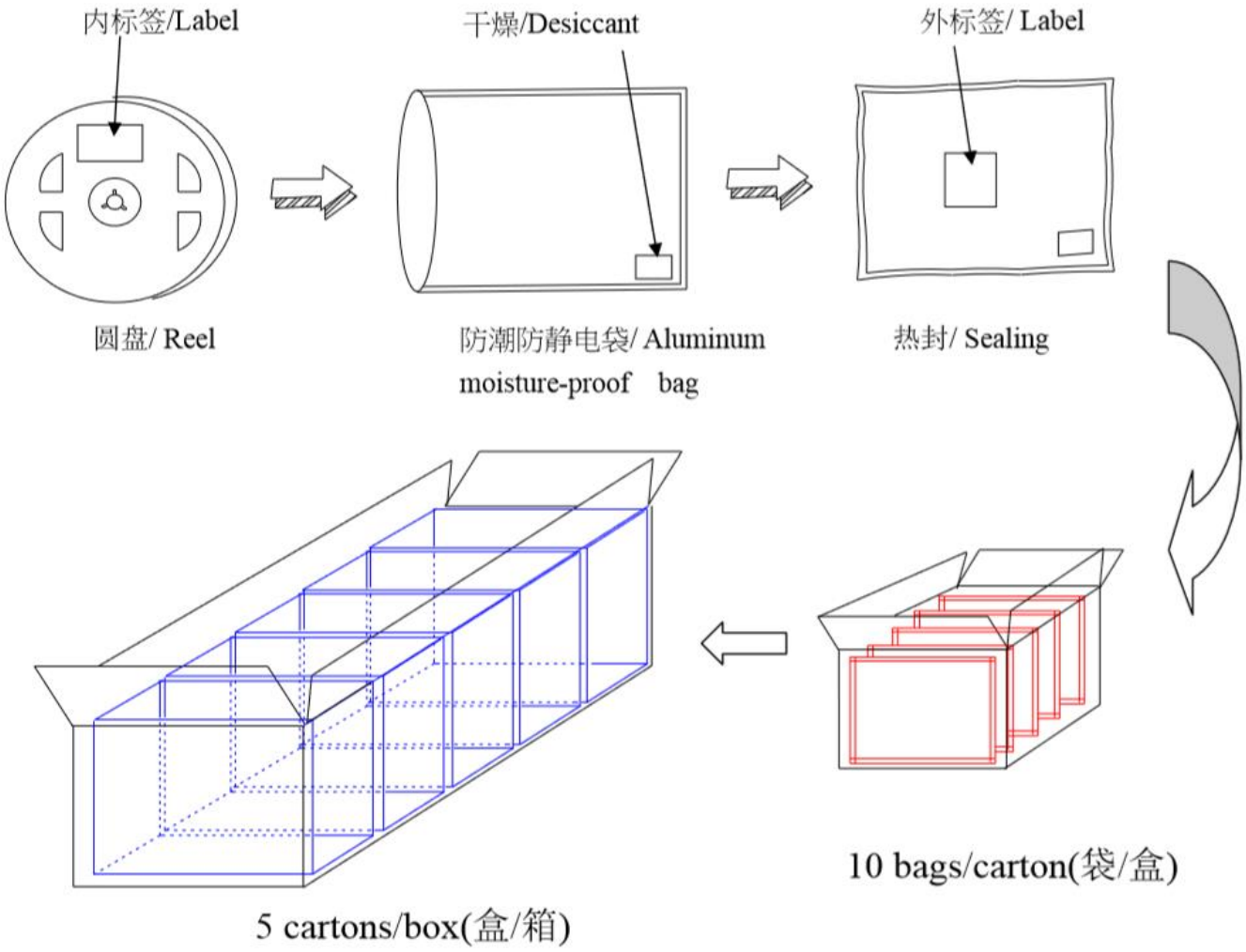

| Dim. A | Dim. B | Dim. C | Q'ty/Reel |
|---|---|---|---|
| 1.77±0.05 | 0.97±0.05 | 0.51±0.05 | 3K |

Unit: mm

## Reel Dimension



## Packing Dimension

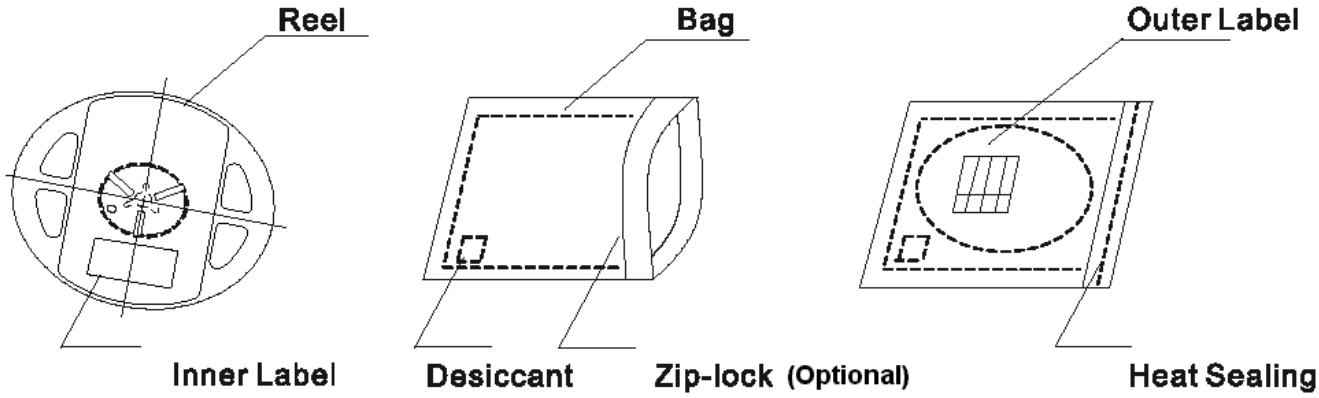


## Dry Pack

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

Upon request, a humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

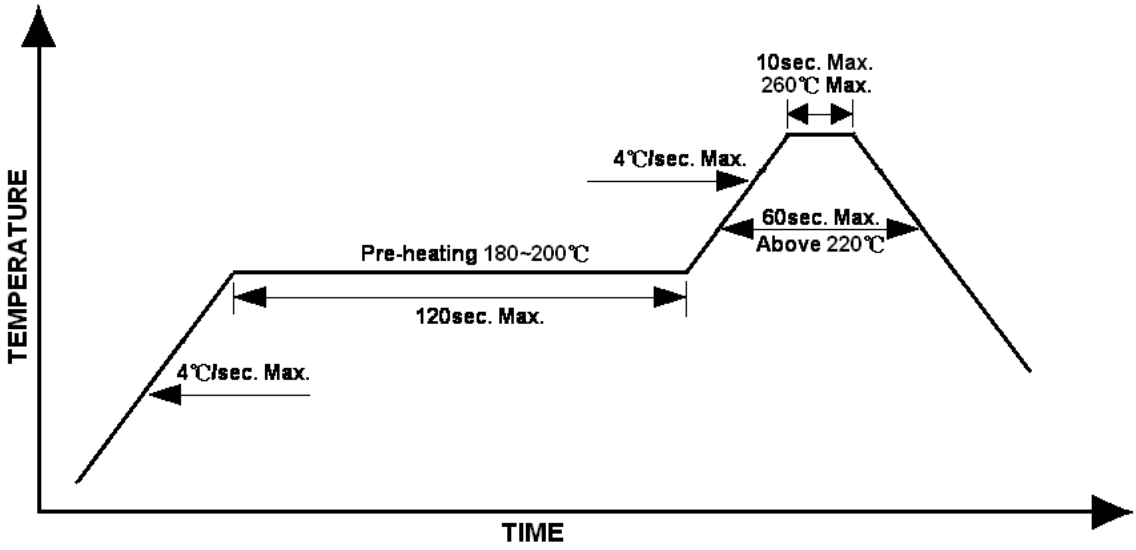
The packaging sequence is as follows:




## Reflow Soldering

- Recommended tin glue specifications: melting temperature in the range of 178~192 $^{O}$C
- The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):

Lead-free Solder Profile



## Precautions

- Avoid exposure to moisture at all times during transportation or storage.
- Anti-Static precaution must be taken when handling GaN, InGaN, and AlInGaP products.
- It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage.
- Avoid operation beyond the limits as specified by the absolute maximum ratings.
- Avoid direct contact with the surface through which the LED emits light.
- If possible, assemble the unit in a clean room or dust-free environment.

## Reworking

- Rework should be completed within 5 seconds under 260 $^{O}$C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

## Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50$^{o}$C x 30sec. or <30$^{o}$C x 3min
- Ultra sonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100 $^{O}$C max, <3min

## Cautions of Pick and Place

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electro-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.

## Reliability

| Item | Frequency/ lots/ samples/ failures | Standards Reference | Conditions |
|---|---|---|---|
| Precondition | For all reliability monitoring tests according to JEDEC Level 2 | J-STD-020 | 1.) Baking at 85°C for 24hrs<br>2.) Moisture storage at 85°C/ 60% R.H. for 168hrs |
| Solderability | 1Q/ 1/ 22/ 0 | JESD22-B102-B And CNS-5068 | Accelerated aging 155°C/ 24hrs<br>Tinning speed: 2.5+0.5cm/s<br>Tinning: A: 215°C/ 3+1s or B: 260°C/ 10+1s |
| Resistance to soldering heat | | CNS-5067 | Dipping soldering terminal only<br>Soldering bath temperature<br>A: 260+/-5°C; 10+/-1s<br>B: 350+/-10°C; 3+/-0.5s |
| Operating life test | 1Q/ 1/ 40/ 0 | CNS-11829 | 1.) Precondition: 85°C baking for 24hrs 85°C/ 60%R.H. for 168hrs<br>2.) Tamb25°C; IF=20mA; duration 1000hrs |
| High humidity, high temperature bias | 1Q/ 1/ 45/ 0 | JESD-A101-B | Tamb: 85°C<br>Humidity: 85% R.H., IF=5mA<br>Duration: 1000hrs |
| High temperature bias | 1Q/ 1/ 20 | IN specs. | Tamb: 55°C<br>IF=20mA<br>Duration: 1000hrs |
| Pulse life test | 1Q/ 1/ 40/ 0 | | Tamb25°C, If=20mA,, Ip=100mA, Duty cycle=0.125 (tp=125 $\mu$s,T=1sec)<br>Duration 500hrs) |
| Temperature cycle | 1Q/ 1/ 76/ 0 | JESD-A104-A IEC 68-2-14, Nb | A cycle: -40 degree C 15min; +85 degree C 15min<br>Thermal steady within 5 min..<br>300 cycles<br>2 chamber/ Air-to-air type |
| High humidity storage test | 1Q/ 1/ 40/ 0 | CNS-6117 | 60+3°C<br>90+5/-10% R.H. for 500hrs |
| High temperature storage test | 1Q/ 1/ 40/ 0 | CNS-554 | 100+10°C for 500hrs |
| Low temperature storage test | 1Q/ 1/ 40/ 0 | CNS-6118 | -40+5°C for 500hrs |

## Revision History

| Changes since last revision | Page | Version No. | Revision Date |
|---|---|---|---|
| Initial Release | | 1.0 | 02-25-2022 |
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